

BS EN 61188-7:2009



BSI British Standards

Printed boards and printed board assemblies – Design and use —

Part 7: Electronic component zero orientation for CAD library construction

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National foreword

This British Standard is the UK implementation of EN 61188-7:2009. It is identical to IEC 61188-7:2009.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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Amendments issued since publication

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EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 61188-7

July 2009

ICS 31.180

English version

**Printed boards and printed board assemblies -
Design and use -
Part 7: Electronic component zero orientation
for CAD library construction
(IEC 61188-7:2009)**

Cartes imprimées
et cartes imprimées équipées -
Conception et utilisation -
Partie 7: Orientation nulle des composants
électroniques pour l'élaboration
de la bibliothèque CAO
(CEI 61188-7:2009)

Leiterplatten und Flachbaugruppen -
Konstruktion und Anwendung -
Teil 7: Nullorientierung elektronischer
Bauelemente für CAD-Bibliotheksaufbau
(IEC 61188-7:2009)

This European Standard was approved by CENELEC on 2009-06-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: Avenue Marnix 17, B - 1000 Brussels

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Foreword

The text of document 91/854/FDIS, future edition 1 of IEC 61188-7, prepared by IEC TC 91, Electronics assembly technology, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 61188-7 on 2009-06-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2010-03-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2012-06-01

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 61188-7:2009 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61182-2	- ¹⁾	Printed board assembly products - Manufacturing description data and transfer methodology - Part 2: Generic requirements	-	-
IEC 61188-5-1	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-1 Design and use - Part 5-1: Attachment (land/joint) considerations - Generic requirements		2002 ²⁾
IEC 61188-5-2	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-2 Design and use - Part 5-2: Attachment (land/joint) considerations - Discrete components		2003 ²⁾
IEC 61188-5-3	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-3 Design and use - Part 5-3: Attachment (land/joint) considerations - Components with gull-wing leads on two sides		2007 ²⁾
IEC 61188-5-4	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-4 Design and use - Part 5-4: Attachment (land/joint) consideration - Components with J-leads on two sides		2007 ²⁾
IEC 61188-5-5	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-5 Design and use - Part 5-5: Attachment (land/joint) considerations - Components with gull-wing leads on four sides		2007 ²⁾
IEC 61188-5-6	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-6 Design and use - Part 5-6: Attachment (land/joint) considerations - Chip carriers with J-leads on four sides		2003 ²⁾
IEC 61188-5-8	- ¹⁾	Printed boards and printed board assemblies - EN 61188-5-8 Design and use - Part 5-8: Attachment (land/joint) considerations - Area array components (BGA, FBGA, CGA, LGA)		2008 ²⁾

¹⁾ Undated reference.

²⁾ Valid edition at date of issue.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –
DESIGN AND USE –****Part 7: Electronic component zero orientation
for CAD library construction**

FOREWORD

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International Standard IEC 61188-7 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/854/FDIS	91/866/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of the IEC 61188 series, under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

The contents of the corrigendum of July 2009 have been included in this copy.